PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Jie-Ning Yang	08/19/2011
Shih-Chieh Hsu	08/19/2011
Yao-Chang Wang	08/19/2011
Chi-Horn Pai	08/19/2011
Chi-Sheng Tseng	08/19/2011
Kun-Szu Tseng	08/19/2011
Ying-Hung Chou	08/19/2011
Chiu-Hsien Yeh	08/19/2011

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13215237

CH $40.00 13215237

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	SHELLEY KUO
Total Attachments: 3 source=1188364#page1.tif source=1188364#page2.tif source=1188364#page3.tif	

PATENT

Docket No NAUP1372USA

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar ($1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Jie-Ning Yang Nationality: TW

Name: Shih-Chieh Hsu Nationality: TW

Name: Yao-Chang Wang Nationality: TW

Name: Chi-Horn Pai Nationality: TW

Name: Chi-Sheng Tseng Nationality: TW

Name: Kun-Szu Tseng Nationality: TW

Name: Ying-Hung Chou Nationality: TW

Name: Chiu-Hsien Yeh Nationality: TW

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: UNITED MICROELECTRONICS CORP.

Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"RESISTOR AND MANUFACTURING METHOD THEREOF"

Which is found in :

(a) ___+___ U.S. patent application executed on even date

(b) ________ U.S. patent application executed on ______________________

(c) ________ U.S. application serial no.______________________________

(d) _______ patent no. ___________________ issued _____________________

(e) ________International application no. _______________

2011-0072

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this AUG 1 9 2011 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)	**Signature of INVENTOR**
Jie-Ning Yang	Jie-Ning Yang
Shih-Chieh Hsu	Shih-Chieh Hsu
Yao-Chang Wang	Yao-Chang Wang
Chi-Horn Pai	Chi-Horn Pai
Chi-Sheng Tseng	Chi-Sheng Tseng
Kun-Szu Tseng	Kun-Szu Tseng
Ying-Hung Chou	Ying-Hung Chou
Chiu-Hsien Yeh	Chiu-Hsien Yeh